

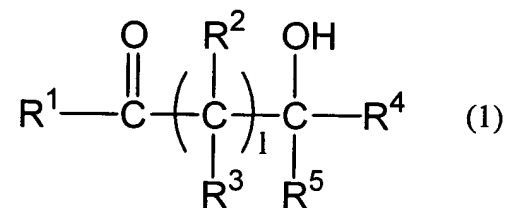
In the Claims:

This listing of claims will replace all prior versions and listings of claims in the application.

Listing of Claims

1. (Original) A photosensitive resin precursor composition comprising:

- (a) a heat resistant resin precursor polymer;
- (b) a radiation sensitive compound; and
- (c) a solvent expressed by formula (1):



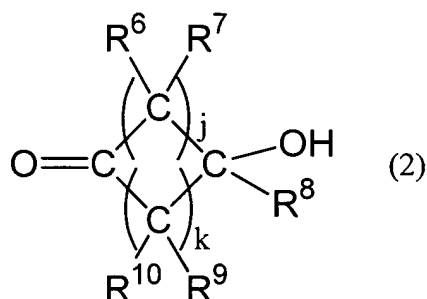
wherein R¹ represents an alkyl group having a carbon number in the range of 1 to 3, R², R³, R⁴, and R⁵ are each selected from among hydrogen and alkyl groups having carbon numbers in the range of 1 to 3, and 1 represents an integer in the range of 0 to 3.

2. (Currently Amended) A photosensitive resin precursor composition ~~according to Claim 1, wherein the solvent is comprising:~~

(a) a heat resistant resin precursor polymer;

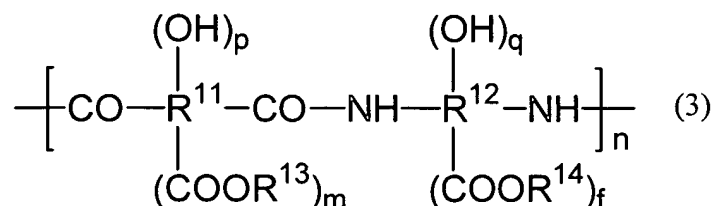
(b) a radiation sensitive compound; and

(c) a solvent expressed by formula (2):



wherein R⁶ to R¹⁰ are each selected from among hydrogen and alkyl groups having carbon numbers in the range of 1 to 3, and j and k are each an integer in the range of 0 to 3 and satisfy the relationship $j + k \geq 2$.

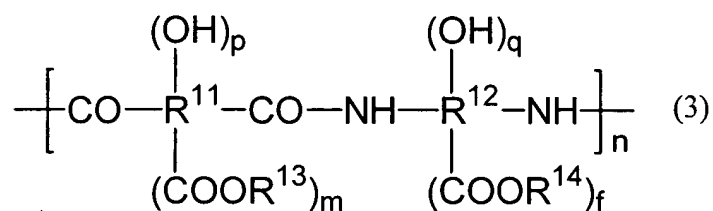
3. (Currently Amended) A photosensitive resin precursor composition according to Claim 1 or 2, wherein the heat resistant resin precursor polymer comprises a structural unit expressed by formula (3):



wherein R^{11} and R^{12} are each an organic group having a carbon number of at least 2 and a valence in the range of 2 to 8, R^{13} and R^{14} are each selected from among hydrogen and organic groups having a carbon number in the range of 1 to 20, n is in the range of 10 to 100000, m and f are each an integer in the range of 0 to 2, and p and q are each an integer in the range of 0 to 4 and satisfy the relationship $p + q > 0$.

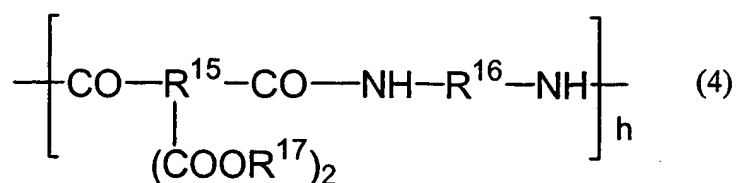
4. (Currently Amended) A photosensitive resin precursor composition according to Claims 1 or 2, wherein the radiation sensitive compound is a quinone diazide.

5. (Currently Amended) A photosensitive resin precursor composition according to Claims 1 or 2, wherein the heat resistant resin precursor polymer comprises a structural unit expressed by formula (3) and wherein the radiation sensitive compound is a quinone diazide.



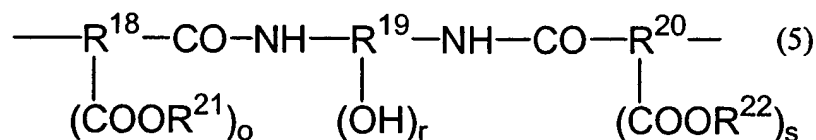
wherein R^{11} and R^{12} are each an organic group having a carbon number of at least 2 and a valence in the range of 2 to 8, R^{13} and R^{14} are each selected from among hydrogen and organic groups having a carbon number in the range of 1 to 20, n is in the range of 10 to 100000, m and f are each an integer in the range of 0 to 2, and p and q are each an integer in the range of 0 to 4 and satisfy the relationship $p + q > 0$.

6. (Original) A photosensitive resin precursor composition according to Claim 1 , wherein the heat resistant resin precursor polymer comprises a structural unit expressed by formula (4):



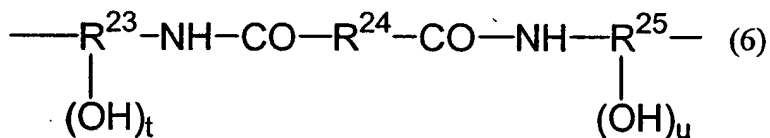
wherein R^{15} represents an organic group having a carbon number of at least 2 and a valence in the range of 2 to 8, R^{16} represents an organic group having a carbon number of at least 2 and a valence in the range of 2 to 6, R^{17} represents an organic group having a carbon-carbon unsaturated double bond capable of dimerization or polymerization by actinic radiation and having a carbon number in the range of 1 to 30, and h is in the range of 10 to 100000.

7. (Original) A photosensitive resin precursor composition according to Claim 3, wherein $R^{11}(\text{COOR}^{13})_m(\text{OH})_p$ in formula (3) is expressed by formula (5):



wherein R^{18} and R^{20} each represent an organic group having a carbon number in the range of 2 to 20 and a valence in the range of 2 to 4, R^{19} represents an organic group having a carbon number in the range of 3 to 20 and a valence in the range of 3 to 6 and having a hydroxy group, R^{21} and R^{22} are each selected from among hydrogen and organic groups having carbon numbers in the range of 1 to 20, o and s each represent an integer in the range of 0 to 2, and r represents an integer in the range of 1 to 4.

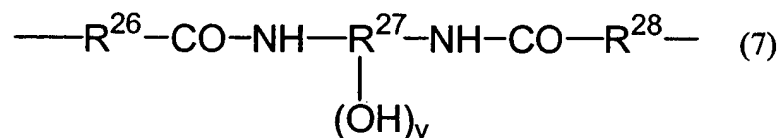
8. (Original) A photosensitive resin precursor composition according to Claim 3, wherein $R^{12}(\text{COOR}^{14})_t(\text{OH})_q$ in formula (3) is expressed by formula (6):



wherein R^{23} and R^{25} each represent an organic group having a carbon number in the range of 2 to 20 and a valence in the range of 3 to 4 and having a hydroxy group, R^{24} represents a

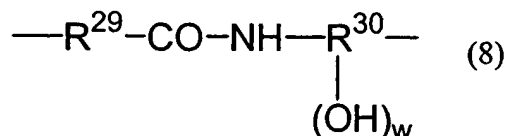
divalent organic group having a carbon number in the range of 2 to 30, and t and u each represent an integer of 1 or 2.

9. (Original) A photosensitive resin precursor composition according to Claim 3, wherein $R^{12}(\text{COOR}^{14})_t(\text{OH})_q$ in formula (3) is expressed by formula (7):



wherein R^{26} and R^{28} each represent a divalent organic group having a carbon number in the range of 2 to 20, R^{27} represents an organic group having a carbon number in the range of 3 to 20 and a valence in the range of 3 to 6 and having a hydroxy group, and v represents an integer in the range of 1 to 4.

10. (Original) A photosensitive resin precursor composition according to Claim 3, wherein $R^{12}(COOR^{14})_f(OH)_q$ in formula (3) is expressed by formula (8):



wherein R^{29} represents a divalent organic group having a carbon number in the range of 2 to 20, R^{30} represents an organic group having a carbon number in the range of 3 to 20 and a valence in the range of 3 to 6 and having a hydroxy group, and w represents an integer in the range of 1 to 4.

11. (Original) A photosensitive resin precursor composition according to Claim 3, wherein m , f , and p in formula (3) are 0.

12. (Original) A photosensitive resin precursor composition according to Claim 3, wherein, in formula (3), m is 2 and f is 1 or 2.